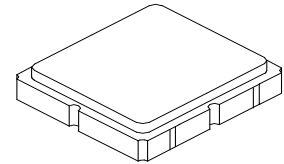


SF2344D

**241 MHz
SAW Filter**



SM3838-8

- *Narrow-band SAW Filter*
- *Balanced/Single-ended Operation*
- *3.8 x 3.8 x 1.4 mm Surface-mount Package*
- *Complies with Directive 2002/95/EC (RoHS)*
- *Moisture Sensitivity Level: 1*
- *AEC-Q200 Qualified*

Absolute Maximum Ratings

Rating	Value	Units
Maximum Incident Power in Passband, Continuous	+15	dBm
Maximum DC Voltage on any Non-ground Terminals	3	VDC
Storage Temperature Range in Tape and Reel	-40 to +85	°C
Suitable for Lead-free Soldering - Maximum Soldering Profile	260 °C for 30 s	

Electrical Characteristics

Characteristic	Sym	Notes	Min	Typ	Max	Units
Center Frequency	f_C			241		MHz
Minimum Insertion Loss	IL_{MIN}			2.2	3.3	dB
3 dB Bandwidth	BW_3			5		MHz
Amplitude Ripple 240.9 to 241.1 MHz					0.2	dB _{P-P}
Group Delay Ripple 240.9 to 241.1 MHz					0.2	µs _{P-P}
Rejection Referenced to IL_{MIN} :						dB
10 to 232.5 MHz			50	60		
274 to 886.5 MHz			50	60		
Operating Temperature Range			-10		+85	°C

Case Style	SM3838-8 3.8 x 3.8 mm Nominal Footprint					
Lid Symbolization (Y=year, WW=week, S=shift) dot=pin 1 indicator	B09, <u>YWWS</u>					
Standard Reel Quantity	Reel Size 7 Inch					500 Pieces/Reel
	Reel Size 13 Inch					3000 Pieces/Reel

Electrical Connections

Connection	Terminals
50 Ω Input Port	2
200 Ω Balanced Output Port	6, 7
Ground	All others

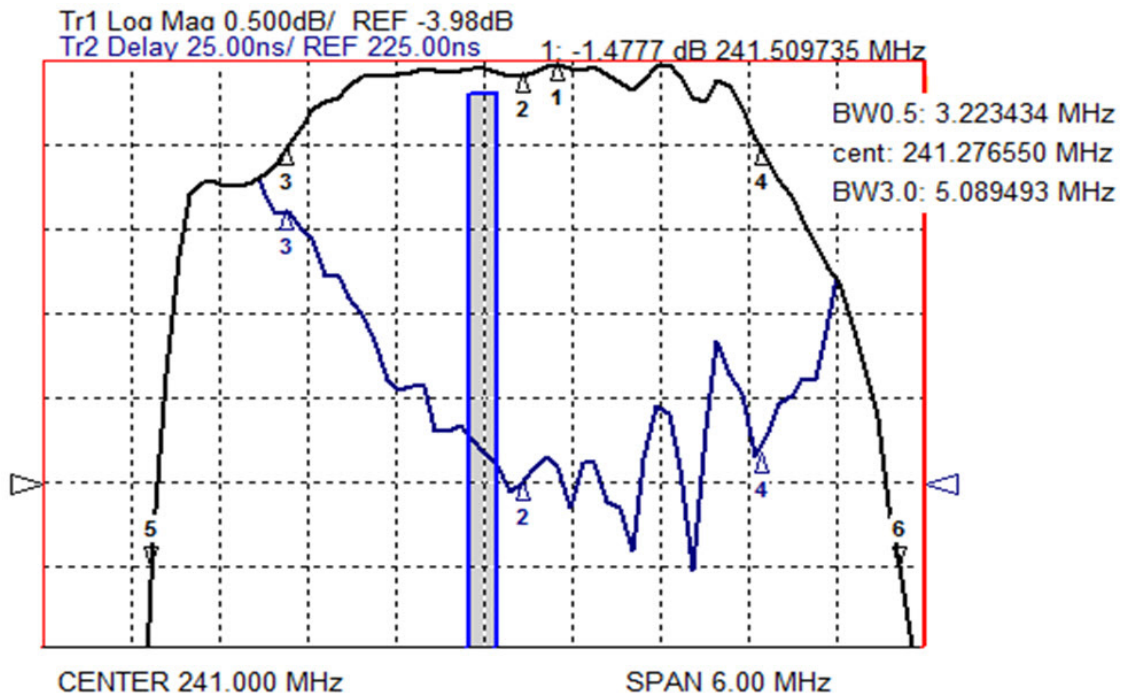
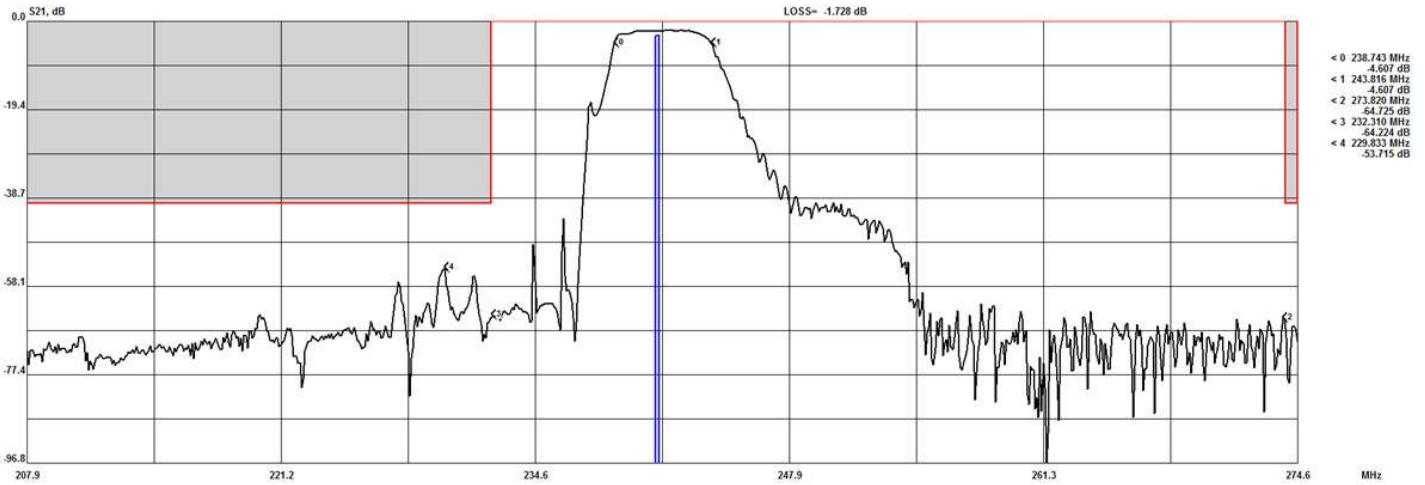


CAUTION: Electrostatic Sensitive Device. Observe precautions for handling.

NOTES:

1. The design, manufacturing process, and specifications of this device are subject to change.
2. US or International patents may apply.
3. RoHS compliant from the first date of manufacture.

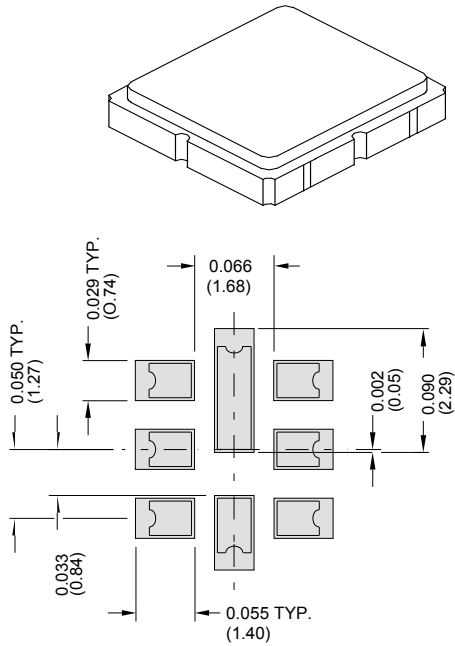
Filter Response Plots



SM3838-8 Case

8-Terminal Ceramic Surface-mount Case

3.8 X 3.8 mm Nominal Footprint



Typical PCB Land Footprint

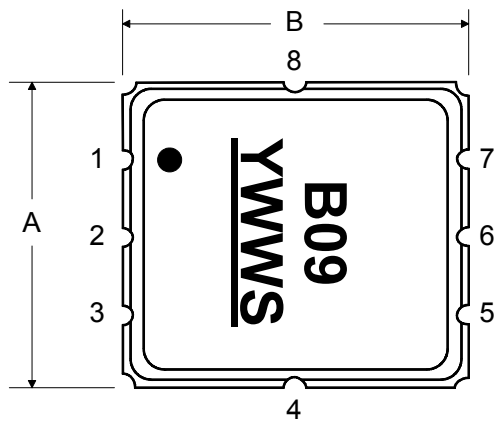
Case Dimensions

Dimension	mm			Inches		
	Min	Nom	Max	Min	Nom	Max
A	3.6	3.8	4.0	0.142	0.150	0.157
B	3.6	3.8	4.0	0.142	0.150	0.157
C	1.05	1.20	1.40	0.041	0.047	0.055
D	0.95	1.10	1.25	0.037	0.043	0.049
E	0.90	1.00	1.10	0.035	0.040	0.043
F	0.50	0.60	0.70	0.020	0.024	0.028
G	2.39	2.54	2.69	0.090	0.100	0.110
H	1.40	1.75	2.05	0.055	0.069	0.080

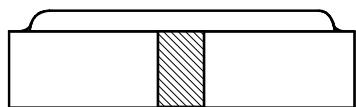
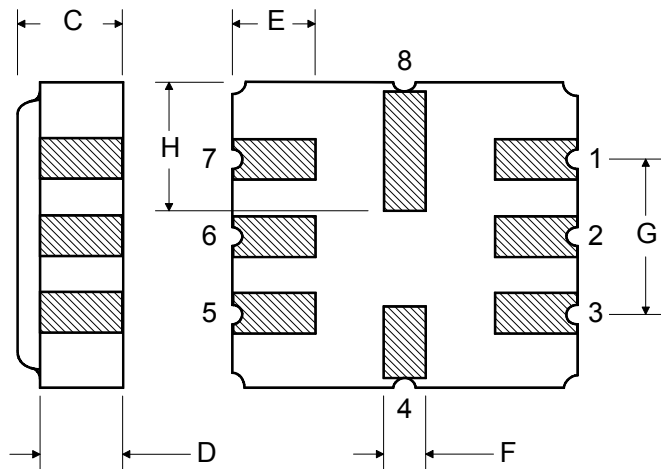
Materials

Solder Pad Plating	0.3 to 1.0 μm Gold over 1.27 to 8.89 μm Nickel
Lid Plating	2.0 to 3.0 μm Nickel
Body	Al_2O_3 Ceramic

TOP VIEW

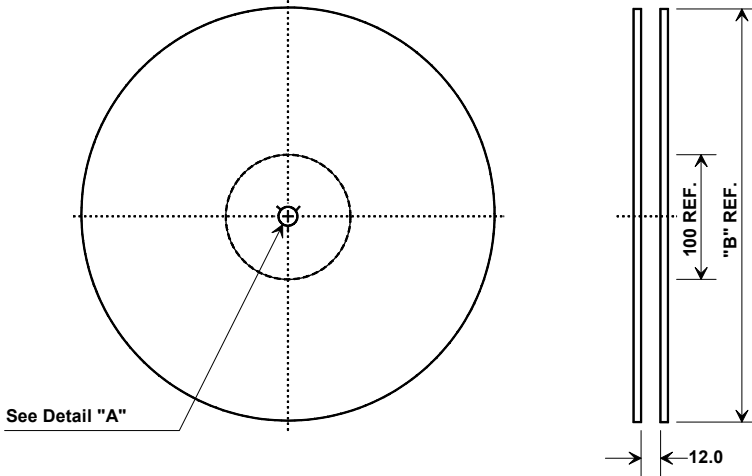


BOTTOM VIEW

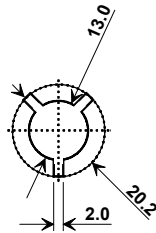


Tape and Reel Specifications

Tape and Reel Standard per ANSI/EIA-481

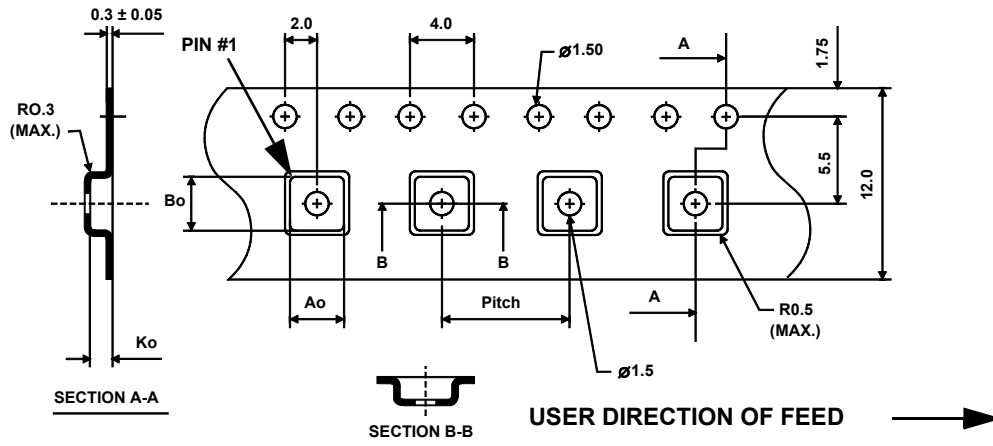


"B"		Quantity Per Reel
Nominal Size		
Inches	millimeters	
7	178	500
13	330	3000



COMPONENT ORIENTATION and DIMENSIONS

Carrier Tape Dimensions	
Ao	4.25 mm
Bo	4.25 mm
Ko	1.30 mm
Pitch	8.0 mm
W	12.0 mm



Recommended Reflow Profile

1. Preheating shall be fixed at 150~180°C for 60~90 seconds.
2. Ascending time to preheating temperature 150°C shall be 30 seconds min.
3. Heating shall be fixed at 220°C for 50~80 seconds and at 260°C +0/-5°C peak (10 seconds).
4. Time: 5 times maximum.

